



# THE DATASHEET OF BAT754C,215



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Kind regards,

Team Nexperia



# BAT754 series

## Schottky barrier diodes

Rev. 3 — 9 October 2012

Product data sheet

## 1. Product profile

### 1.1 General description

Planar Schottky barrier diodes with an integrated guard ring for stress protection, encapsulated in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

### 1.2 Features and benefits

- Low forward voltage
- Low capacitance
- AEC-Q101 qualified

### 1.3 Applications

- Ultra high-speed switching
- Line termination
- Voltage clamping
- Reverse polarity protection

### 1.4 Quick reference data

Table 1. Quick reference data

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per diode</b>						
$V_R$	reverse voltage		-	-	30	V
$V_F$	forward voltage	$I_F = 100\text{ mA}$	[1]	-	600	mV
$I_R$	reverse current	$V_R = 25\text{ V}$	[1]	-	2	$\mu\text{A}$

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .

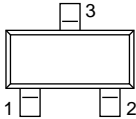
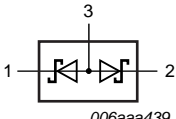
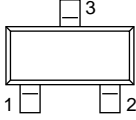
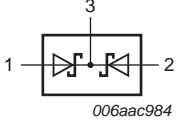
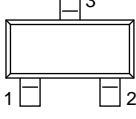
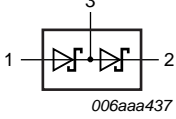
## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
<b>BAT754</b>			
1	anode		
2	not connected		
3	cathode		



**Table 2. Pinning ...continued**

Pin	Description	Simplified outline	Graphic symbol
<b>BAT754A</b>			
1	cathode (diode 1)		 006aaa439
2	cathode (diode 2)		
3	common anode		
<b>BAT754C</b>			
1	anode (diode 1)		 006aac984
2	anode (diode 2)		
3	common cathode		
<b>BAT754S</b>			
1	anode (diode 1)		 006aaa437
2	cathode (diode 2)		
3	cathode (diode 1), anode (diode 2)		

## 3. Ordering information

**Table 3. Ordering information**

Type number	Package		Version
	Name	Description	
BAT754 series	-	plastic surface-mounted package; 3 leads	SOT23

## 4. Marking

**Table 4. Marking codes**

Type number	Marking code <sup>[1]</sup>
BAT754	2K*
BAT754A	2L*
BAT754C	2M*
BAT754S	2N*

[1] \* = placeholder for manufacturing site code.

## 5. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
<b>Per diode</b>					
$V_R$	reverse voltage		-	30	V
$I_F$	forward current		-	200	mA
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$		300	mA
$I_{FSM}$	non-repetitive peak forward current	sine wave; $t_p < 8.3$ ms	[1] -	600	mA
<b>Per device; one diode loaded</b>					
$T_j$	junction temperature		-	125	°C
$T_{amb}$	ambient temperature		-55	+125	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1]  $T_j = 25$  °C before surge.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per device; one diode loaded</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] -	-	500	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

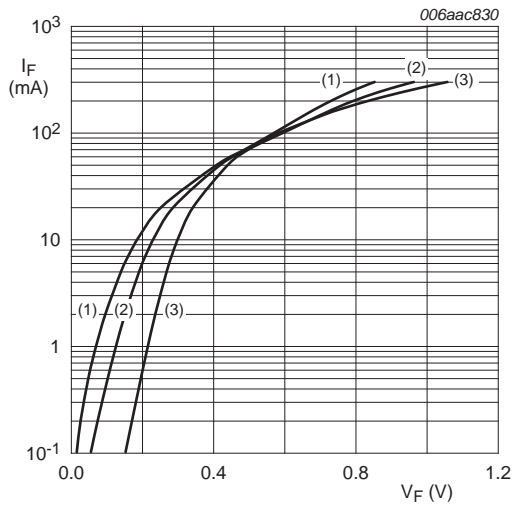
## 7. Characteristics

**Table 7. Characteristics**

$T_{amb} = 25$  °C unless otherwise specified.

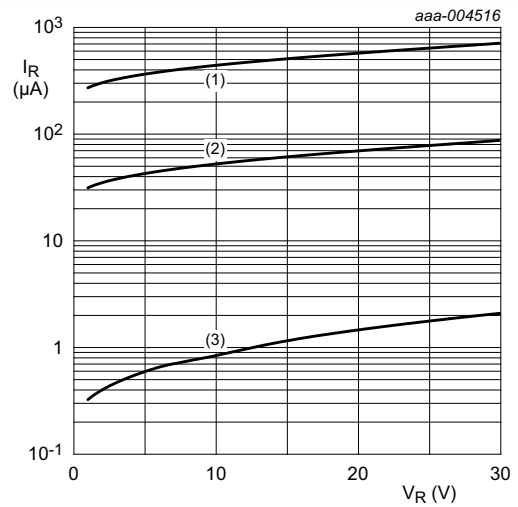
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage		[1]			
		$I_F = 0.1$ mA	-	-	200	mV
		$I_F = 1$ mA	-	-	260	mV
		$I_F = 10$ mA	-	-	340	mV
		$I_F = 30$ mA	-	-	420	mV
		$I_F = 100$ mA	-	600	-	mV
$I_R$	reverse current	$V_R = 25$ V	[1] -	-	2	μA
$C_d$	diode capacitance	$f = 1$ MHz; $V_R = 1$ V	-	-	10	pF

[1] Pulse test:  $t_p \leq 300$  μs;  $\delta \leq 0.02$ .



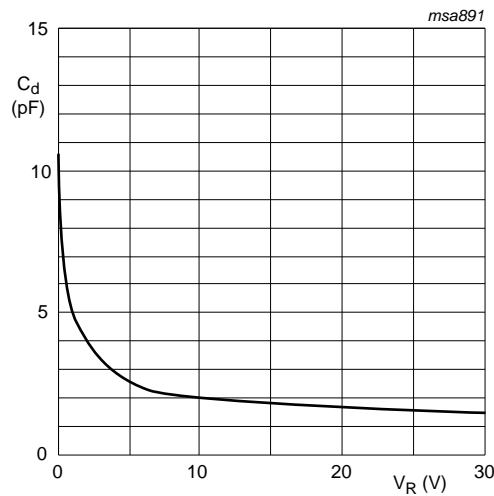
- (1)  $T_{amb} = 125\text{ °C}$
- (2)  $T_{amb} = 85\text{ °C}$
- (3)  $T_{amb} = 25\text{ °C}$

**Fig 1. Forward current as a function of forward voltage; typical values**



- (1)  $T_{amb} = 125\text{ °C}$
- (2)  $T_{amb} = 85\text{ °C}$
- (3)  $T_{amb} = 25\text{ °C}$

**Fig 2. Reverse current as a function of reverse voltage; typical values**



$f = 1\text{ MHz}; T_{amb} = 25\text{ °C}$

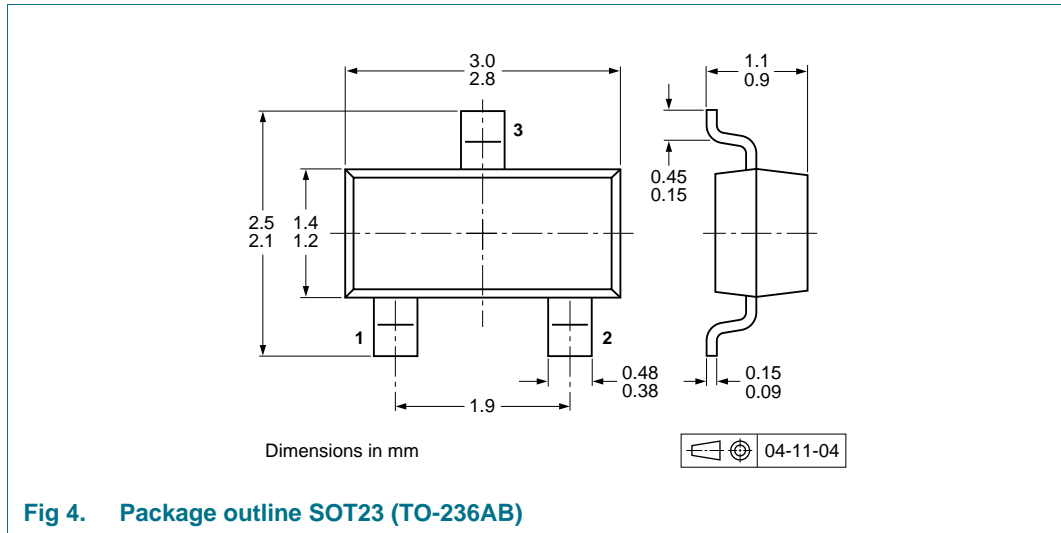
**Fig 3. Diode capacitance as a function of reverse voltage; typical values**

## 8. Test information

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

**9. Package outline**



**Fig 4. Package outline SOT23 (TO-236AB)**

**10. Packing information**

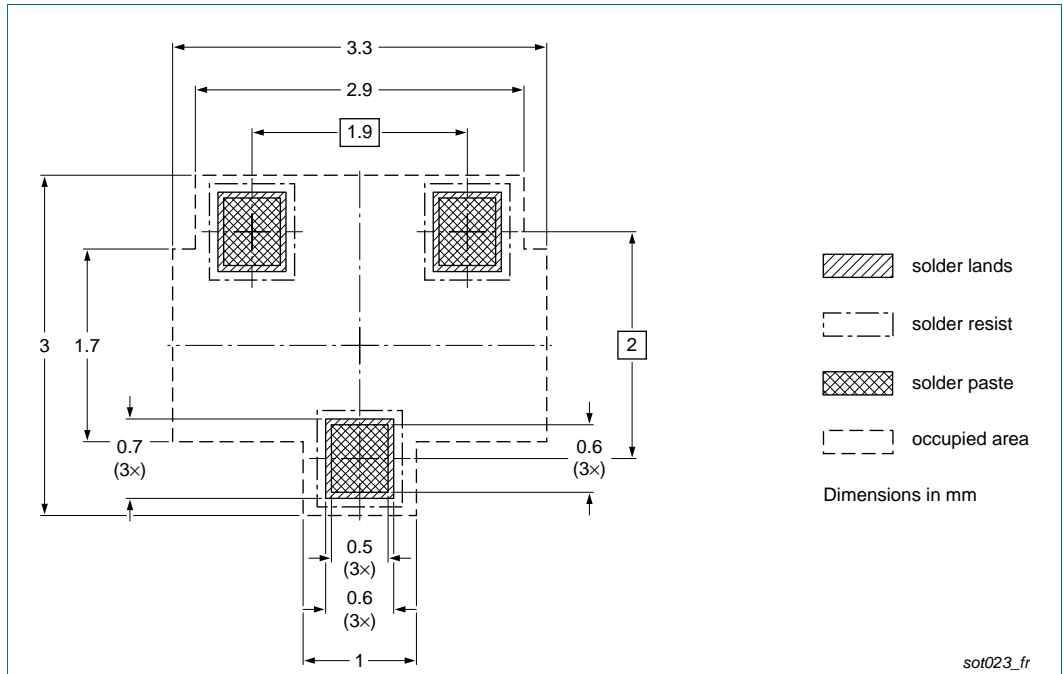
**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

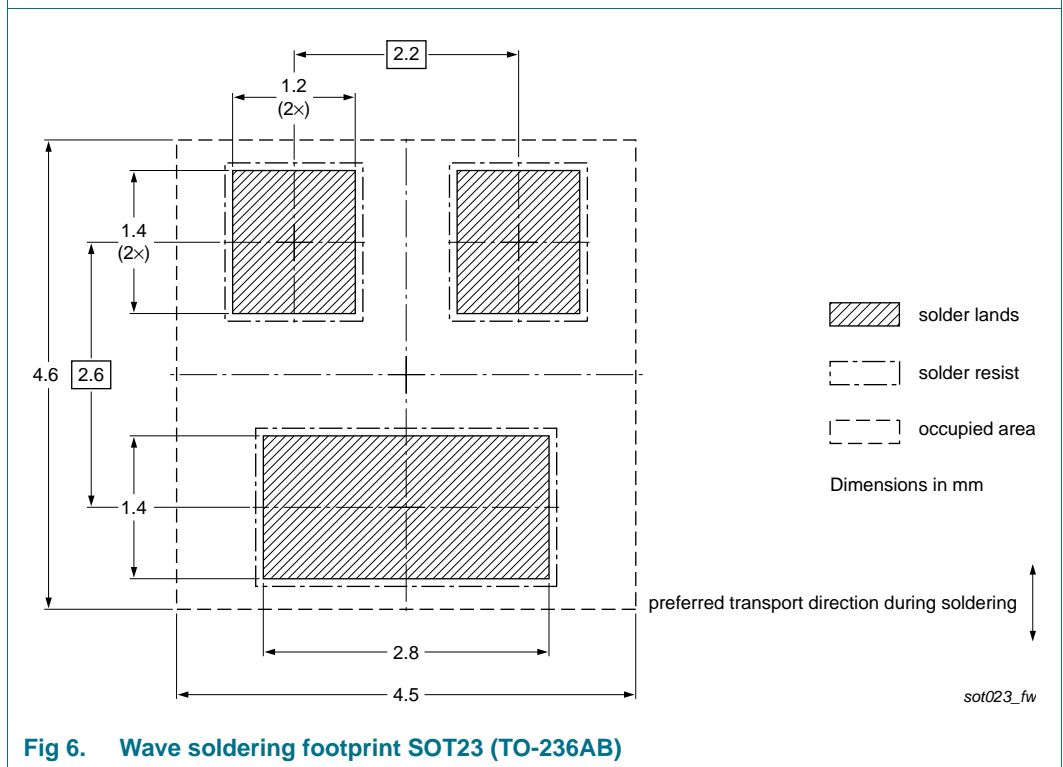
Type number	Package	Description	Packing quantity	
			3000	10000
BAT754 series	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235

[1] For further information and the availability of packing methods, see [Section 14](#).

**11. Soldering**



**Fig 5. Reflow soldering footprint SOT23 (TO-236AB)**



**Fig 6. Wave soldering footprint SOT23 (TO-236AB)**

## 12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAT754_SER v.3	20121009	Product data sheet	-	BAT754_SERIES v.2
Modifications:	<ul style="list-style-type: none"> <li>• The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>• Legal texts have been adapted to the new company name where appropriate.</li> <li>• <a href="#">Section 1</a>: updated</li> <li>• <a href="#">Section 4</a>: updated</li> <li>• <a href="#">Table 5</a>: I<sub>FSM</sub> conditions updated; changed T<sub>amb</sub> minimum value to comply with AEC-Q101</li> <li>• <a href="#">Figure 1</a> and <a href="#">2</a>: updated</li> <li>• <a href="#">Section 8 "Test information"</a>: added</li> <li>• <a href="#">Figure 4</a>: replaced by minimized package outline drawing</li> <li>• <a href="#">Section 10 "Packing information"</a>: added</li> <li>• <a href="#">Section 11 "Soldering"</a>: added</li> <li>• <a href="#">Section 13 "Legal information"</a>: updated</li> </ul>			
BAT754_SERIES v.2	20030325	Product data sheet	-	BAT754_SERIES v.1
BAT754_SERIES v.1	19990805	Product specification	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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